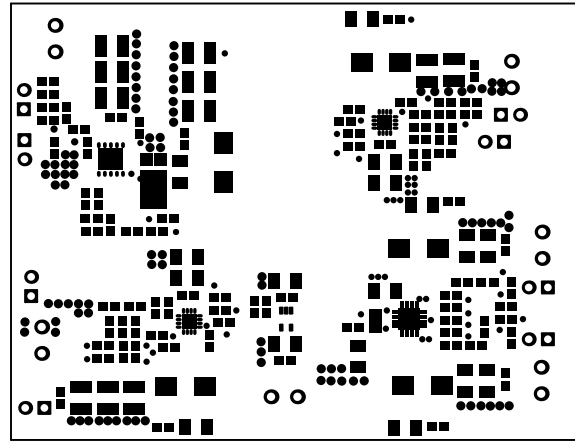
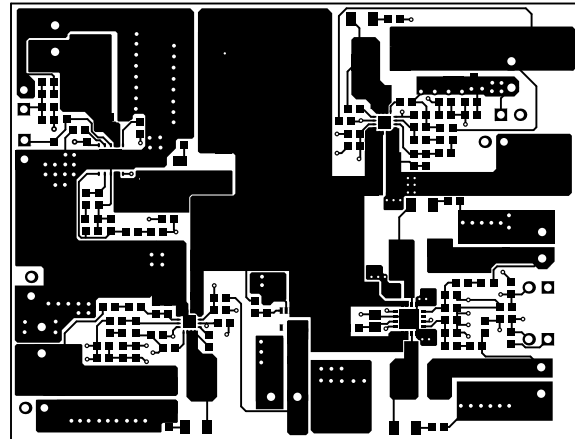


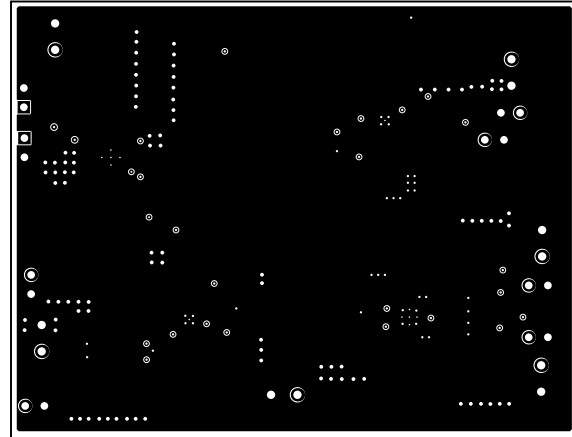
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4442	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00804		
PLOT NAME = Top Overlay	GENERATED : 3/8/2016	3:11:24 PM	TEXAS INSTRUMENTS



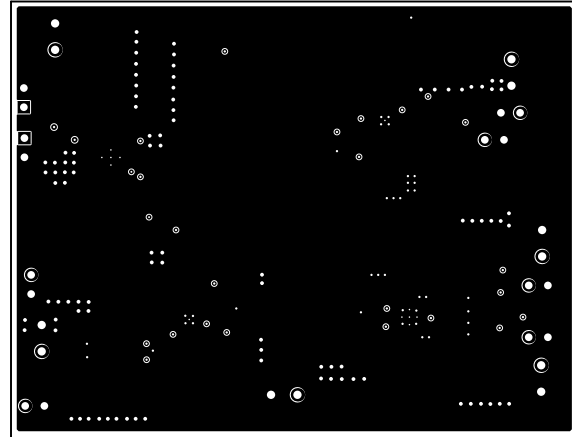
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4442	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00804		
PLOT NAME = Top Solder Mask	GENERATED : 3/8/2016	3:11:25 PM	TEXAS INSTRUMENTS



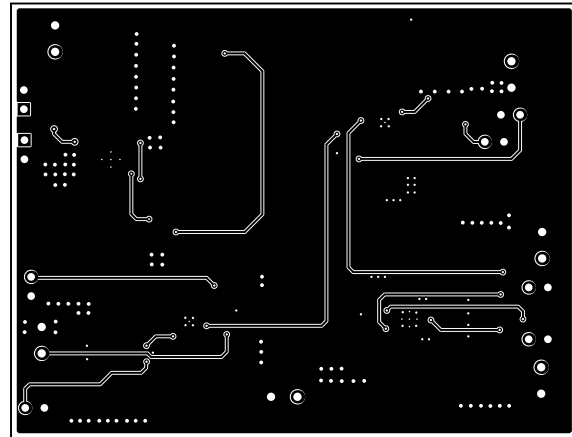
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4442	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00804		
PLOT NAME = Top Layer	GENERATED : 3/8/2016	3:11:26 PM	TEXAS INSTRUMENTS



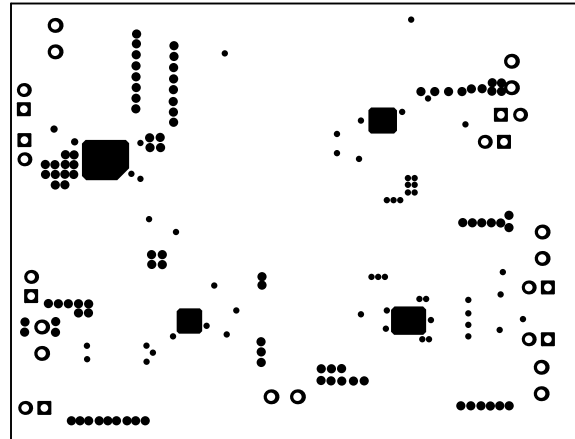
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4442	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Mid-Layer 1	TID #: TIDA-00804		
PLOT NAME = Signal Layer 1	GENERATED : 3/8/2016 3:11:27 PM	TEXAS INSTRUMENTS	



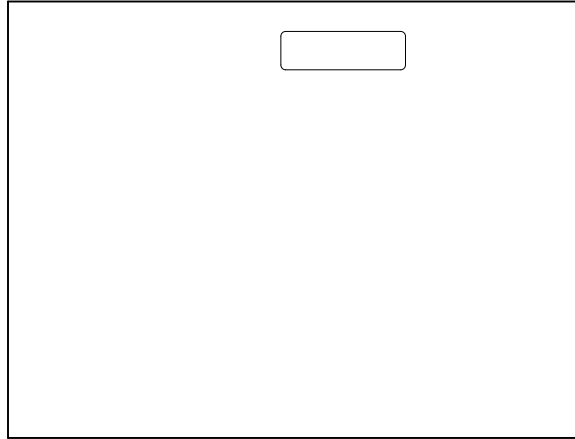
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4442	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Mid-Layer 2	TID #: TIDA-00804		
PLOT NAME = Signal Layer 2	GENERATED : 3/8/2016 3:11:28 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4442	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00804		
PLOT NAME = Bottom Layer	GENERATED : 3/8/2016	3:11:29 PM	TEXAS INSTRUMENTS

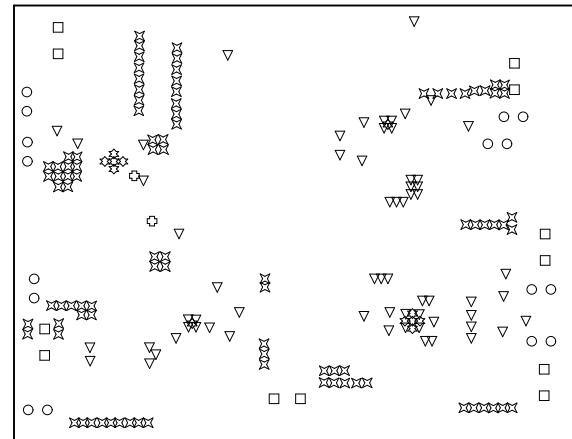


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4442	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00804		
PLOT NAME = Bottom Solder Mask	GENERATED : 3/8/2016	3:11:30 PM	TEXAS INSTRUMENTS

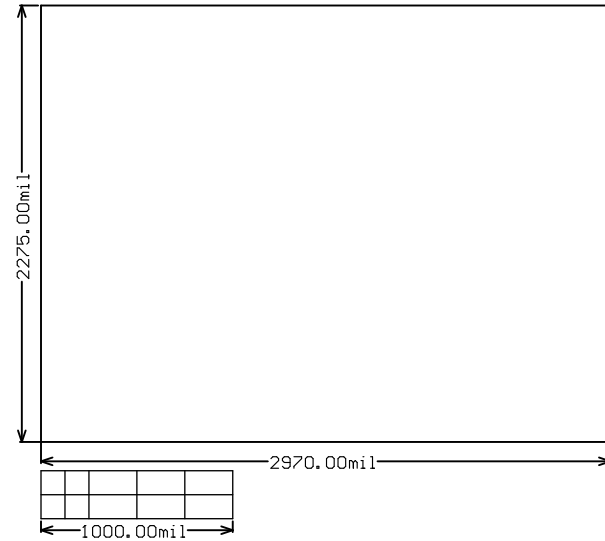


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4442	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00804		
PLOT NAME = Bottom Overlay	GENERATED : 3/8/2016	3:11:31 PM	TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
⊛	12	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊚	2	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
▽	64	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	92	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
○	16	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	12	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
	198 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4442	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00804		
PLOT NAME = Drill Drawing	GENERATED : 3/8/2016	3:11:32 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP4442	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Dimensions	TID #: TIDA-00804		
PLOT NAME = Board Dimensions	GENERATED : 3/8/2016	3:11:34 PM	TEXAS INSTRUMENTS

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